PATENT ASSIGNMENT

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SUBMISSION TYPE: **NEW ASSIGNMENT** NATURE OF CONVEYANCE: **ASSIGNMENT**

CONVEYING PARTY DATA

Name	Execution Date
Tetsuya Hamada	12/13/2006

RECEIVING PARTY DATA

Name:	Dainippon Screen Mfg. Co., Ltd.
Street Address:	Tenjinkita-cho 1-1, Teranouchi-agaru 4-chome
Internal Address:	Horikawa-dori, Kamigyo-ku
City:	Kyoto
State/Country:	JAPAN
Postal Code:	602-8585

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11621216

CORRESPONDENCE DATA

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NAME OF SUBMITTER: James A. Finder

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PATENT

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PATENT APPLICATION ASSIGNMENT SOLE OR JOINT INVENTORS EXECUTED OUTSIDE U.S.A.

ofgs file No. <u>D/3258-33(-)</u> V2423

WHEREAS, I (We), Tetsuya HAMADA	
as assignor(s), have invented certain im	provements in
SUBSTRATE PROCESSING APPARATUS	
	for
which an application for United States Letters Patent has date herewith; and	been executed by me (us) on even
WHEREAS, DAINIPPON SCREEN MFG. CO., LTD. of Tenjinkita-ch	o 1-1, Teranouchi-agaru 4-chome,
Horikawa-dori, Kamigyo-ku, Kyoto 602-8585, JAPAN	· · · · · · · · · · · · · · · · · · ·
as assignee, is desirous of acquiring all right, title and and any Patent that may be granted therefor.	interest in and to said invention
Now, THEREFORE, in consideration of One Dollar (\$ consideration, the receipt of which is hereby acknowledge sell, assign and set over to said assignee the entire United States and all other countries in and to said invention for Patent, all original, divisional, continuation, substituted the same applied for or granted therefor in the United including all rights of priority from the filing of said application of Patents and Track requested to issue all patens on said inventions or restricted, as assignee of the entire interest therin; (ourselves) and my (our) legal representatives, heirs covenant without further remuneration, to execute and deliveressue and other applications for Patent on said inventions and assignee or its assigns, to communicate to said assignet interferences or other legal proceedings in which and execute involved, to sign all lawful papers, make all right exercities as a said invention in the United States are protection for said invention in the United States are protection for said invention in the United States are protection for said invention in the United States are protection for said invention in the United States are protection for said invention in the United States are protection for said invention in the United States are protection for said invention in the United States are protection for said invention in the United States are protection for said invention in the United States are protected in the said applications to be borne and paid the protection for said invention in the United States are protected as a same protection for said invention in the United States are protected as a same protection for said invention in the United States are protected as a same protection for said invention in the United States are protected as a same protected are protected as a same protected a	id, I (we), as assigner(s), hereby right, title and interst for the sion and the aforesaid application situte or reissue applications and States and all other countries, aplication, and all rights for past demarks is hereby authorized and ulting therefrom to said assignee and the undersigned for myself and assigns do hereby agree and wer all divisional, continuation, cons and all assignments thereof to signee or its representatives all whenever requested, to testify in y of said applications or patents ghtful oaths, and to do generally, assigns and nominees to obtain tes and all other countries, the
Date: /3/12/2006	Jawya Hamada Tetsuya HAMADA

LEGALIZATION RECOMMENDED

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RECORDED: 01/10/2007